

☒ L7: (1) ("5514906").PN.  
☒ L8: (1) ("5497033").PN.  
☒ L9: (1) ("5455457").PN.  
☒ L10: (1) ("5422513").PN.  
☒ L11: (1) ("5353498").PN.  
☒ L12: (1081) semiconductor and  
 Failed

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DBs: USPAT;EPO;JPO

Default operator: OR

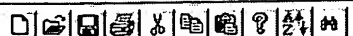
☒ Plurals☒ Highlight all hit terms

semiconductor and heat adj spreader






	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRe
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6559670 B1	20030506	9	Backside liquid crystal analysis technique for	324/765	324/158.1; 324/754
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6559536 B1	20030506	37	Semiconductor device having a heat spreading plate	257/712	257/675; 257/713
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6558742 B1	20030506	13	Method of hot-filament chemical vapor deposition of	427/249.8	427/249.11; 427/255.11;
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6558617 B2	20030506	9	Copper alloy for use in electric and electronic	420/481	148/434
5	<input type="checkbox"/>	<input type="checkbox"/>	US 6558500 B2	20030506	6	Method of producing a lead frame with composite film	156/261	156/309.9; 156/330.9;
6	<input type="checkbox"/>	<input type="checkbox"/>	US 6555200 B2	20030429	15	Method of making semiconductor devices,	428/136	257/290; 257/701;
7	<input type="checkbox"/>	<input type="checkbox"/>	US 6554598 B1	20030429	9	Mold assembly for encapsulating semiconductor	425/89	264/272.14; 264/272.15;
8	<input type="checkbox"/>	<input type="checkbox"/>	US 6552907 B1	20030422	10	BGA heat ball plate spreader, BGA to PCB plate	361/708	174/252; 361/719;
9	<input type="checkbox"/>	<input type="checkbox"/>	US 6552430 B1	20030422	10	Ball grid array substrate with improved traces formed	257/738	257/678; 257/690;
10	<input type="checkbox"/>	<input type="checkbox"/>	US 6552428 B1	20030422	9	Semiconductor package having an exposed heat spreader	257/706	257/704; 257/707;
11	<input type="checkbox"/>	<input type="checkbox"/>	US 6552417 B2	20030422	12	Molded plastic package with heat sink and enhanced	257/666	257/670; 257/676;



☒ L3: (166) 1 and integrated  
☒ L4: (0) 3 and build-up adj  
☒ L5: (69) 3 and trace\$1  
☒ L6: (491) 2 and (conductiv  
☒ L7: (26) 6 and (die with c  
☒ L8: (14) 1 and (die with c

Failed

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DBs: USPAT; EPO; JPO

☒ Plurals

Default operator: OR

☒ Highlight all hit terms initial

1 and (die with core)






	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6469379 B1	20021022	8	Chain extension for thermal materials	257/706	257/712; 257/714;
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6423570 B1	20020723	25	Method to protect an encapsulated die package	438/106	257/612; 257/712;
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6400010 B1	20020604	21	Substrate including a metal portion and a resin portion	257/706	257/675; 257/700;
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6310386 B1	20011030	19	High performance chip/package inductor	257/531	257/724; 257/778;
5	<input type="checkbox"/>	<input type="checkbox"/>	US 6093960 A	20000725	5	Semiconductor package having a heat spreader capable of	257/706	257/666; 257/675;
6	<input type="checkbox"/>	<input type="checkbox"/>	US 5955782 A	19990921	6	Apparatus and process for improved die adhesion to	257/720	257/712; 257/713;
7	<input type="checkbox"/>	<input type="checkbox"/>	US 5939214 A	19990817	10	Thermal performance package for integrated circuit chip	428/626	174/52.4; 257/712;
8	<input type="checkbox"/>	<input type="checkbox"/>	US 5818105 A	19981006	16	Semiconductor device with plastic material covering a	257/696	257/695; 257/701;
9	<input type="checkbox"/>	<input type="checkbox"/>	US 5728248 A	19980317	13	Method for making a multi-tier laminate	156/257	156/263; 156/273.3;
10	<input type="checkbox"/>	<input type="checkbox"/>	US 5681663 A	19971028	6	Heatspreader carrier strip	428/614	257/677; 257/E23.103;
11	<input type="checkbox"/>	<input type="checkbox"/>	US 5597643 A	19970128	12	Multi-tier laminate substrate with internal heat	428/209	174/255; 257/E23.004;